



TIF®080AB-11F is a highly thermally conductive, liquid gap filling material. It's provided with two-component and different temperature curing system. The product is supplied as highly thermal conductive material, soft elastomer for coupling on electronic device module. Heat can transmit to the metal housing or dissipation plate from the separate elements or even the entire PCB, which in effect enhances the efficiency and life-time of the heat-generating electronic components. It's liquid approach offer variety of thickness, replacing individual die-cutting and specific pad thickness. Different from grease, the cured product is dry and can be touched, which is intended for use in further thermal applications.

Features

- » Good thermal conductivity: **8.0 W/mK**
- » Two-part formulation for easy storage
- » Excellent low and high temperature mechanical and chemical stability
- » Ultra-conforming low-stress interface application
- » Ambient or accelerated cure schedules
- » Optimized shear thinning characteristics for ease of dispensing

Application

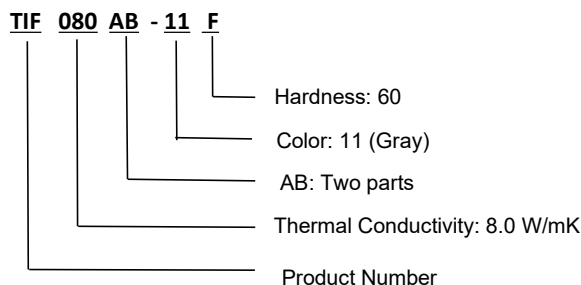
- » Computer and peripherals
- » Telecommunications
- » Automotive electronics
- » Thermally conductive vibration dampening
- » Heat sink and any heat generating semiconductor

Product Specification

50 cc/pcs, 48 pcs/box or 400 cc/pcs, 9 pcs/box.

We offer the custom packaged in syringes for automated dispensing applications. Please contact us for confirming.

Product Identifier



Global solutions: Local support

China: +86-769-38801208

Taiwan: +886-2-2277-1007

Canada: +001-604-2998559

Vietnam: +84-396852859

service@ziitek.com

www.ziitek.com

Ziitek Technology Ltd and its distributors provide information deemed accurate and reliable. However, product specifications may be adjusted due to technical modifications or optimizations without prior notice. The responsibility for product use and application lies with the end user. Ziitek makes no guarantees regarding the product's suitability, merchantability, or fitness for a particular purpose and assumes no liability for incidental or consequential damages. Ziitek and its logo are the property of the company or its affiliates.



TIF080AB-11F-0825

Typical Properties of TIF®080AB-11F Series		
Uncured Material Properties		
Property	Value	Method
Color/Part A	White	Visual
Color/Part B	Gray	Visual
Flow Rate (g/min)	9.0	Ziitek Test Method (50 cc syringe/ 1.5 mm orifice/ 90 psi)
Density (g/cc)	3.25	ASTM D792
Bond Line Thickness (mm)	0.1	Ziitek Test Method
Thermal Resistance @10psi (°C·in ² /W)	0.07	ASTM D5470
Thermal Resistance @50psi (°C·in ² /W)	0.06	ASTM D5470
Mix Ratio	1:1	-
Shelf Life	12 months	-
Cure Schedule		
Pot Life @ 25°C	30 min	Ziitek Test Method
Cure @ 25°C	120 min	Ziitek Test Method
Cure @ 70°C	30 min	Ziitek Test Method
Cure Material Properties		
Color	Gray	Visual
Hardness (Shore OO)	60	ASTM D2240
Recommended Operating Temp (°C)	-45 ~ 200	Ziitek Test Method
Breakdown Voltage (V/mm)	≥ 5500	ASTM D149
Flame Rating	V-0	UL 94
Thermal Conductivity (W/mK)	8.0	ASTM D5470